



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR DFN-10

Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
BOND INT	240	190,320	200°C +N2	0	0.00
HAST	330	33,000	130°C, 85%RH	0	0.00
Solder Dunk	110	330	260°C, 10 SEC.	0	0.00
Pressure Pot	330	31,680	121°, 15 PSIG	0	0.00
Solderability	90	720	883 M2003	0	0.00
Temp Cycle	330	165,000	-65°C-150°C	0	0.00
Thermal Shock	5,350	535,000	-60°C-150°C	0	0.00